

#### 2.0x1.25mm BI-COLOR SMD CHIP LED LAMP

Part Number: APB2012SURKCGKC

Hyper Red Green

#### **Features**

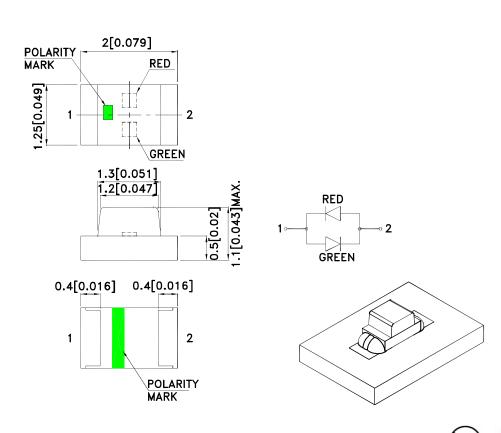
- 2.0mmx1.25mm SMT LED, 1.1mm thickness.
- Bi -color,Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

#### Description

The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

The Green source color devices are made with AlGalnP on GaAs substrate Light Emitting Diode.

### **Package Dimensions**



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15(0.006") unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
   The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAM5537 **REV NO: V.2A** DATE: APR/01/2013 PAGE: 1 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Q.M.Chen ERP: 1203012313

#### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APB2012SURKCGKC	Hyper Red (AlGaInP)	- Water Clear	120	200	- 150°
			*40	*80	
	Green (AlGaInP)		20	50	
			*20	*50	

- 1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green	645 574		nm	Ir=20mA
λD [1]	Dominant Wavelength	Hyper Red Green	630 570		nm	Ir=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green	28 20		nm	IF=20mA
С	Capacitance	Hyper Red Green	35 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red Green	1.95 2.1	2.5 2.5	V	IF=20mA

#### Notes:

- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
  3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

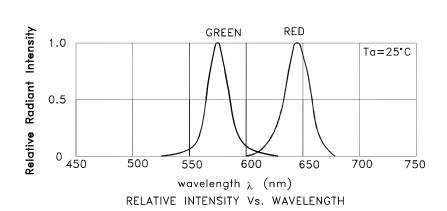
#### Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Green Units			
Power dissipation	75	75	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	185	150	mA		
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

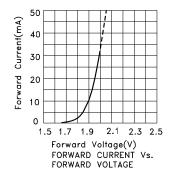
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

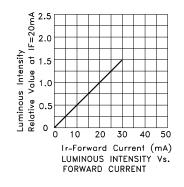
SPEC NO: DSAM5537 **REV NO: V.2A** DATE: APR/01/2013 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Q.M.Chen ERP: 1203012313

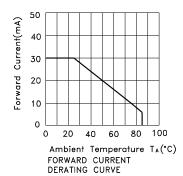
Luminous intensity/ luminous Flux: +/-15%.
 Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

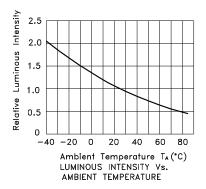


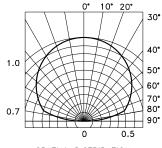
### APB2012SURKCGKC Hyper Red







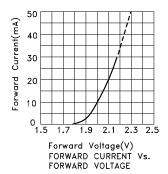


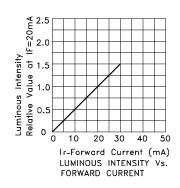


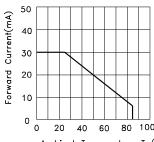
SPATIAL DISTRIBUTION

SPEC NO: DSAM5537 REV NO: V.2A DATE: APR/01/2013 PAGE: 3 OF 6
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Q.M.Chen ERP: 1203012313

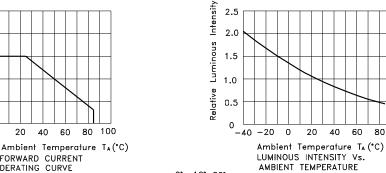
#### Green





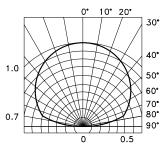


FORWARD CURRENT DERATING CURVE



2.5

2.0



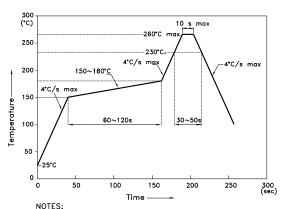
SPATIAL DISTRIBUTION

SPEC NO: DSAM5537 **REV NO: V.2A** DATE: APR/01/2013 PAGE: 4 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** ERP: 1203012313 DRAWN: Q.M.Chen

#### APB2012SURKCGKC

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



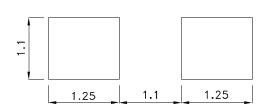
- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

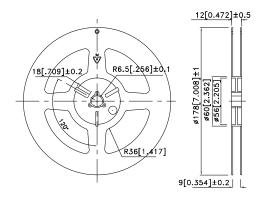
  2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
  - to high temperature.

    3.Number of reflow process shall be 2 times or less.

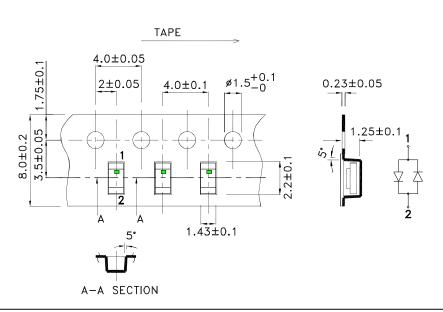
### Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



#### **Reel Dimension**



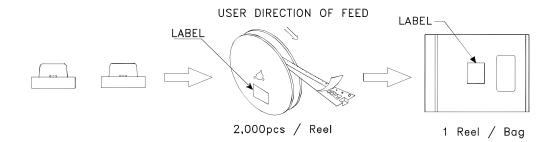
Tape Dimensions (Units : mm)

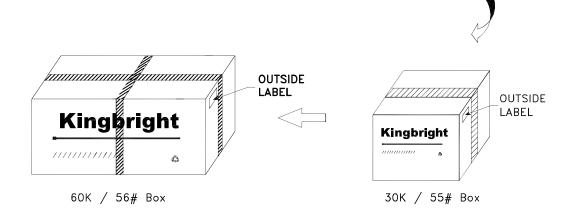


SPEC NO: DSAM5537 APPROVED: WYNEC REV NO: V.2A CHECKED: Allen Liu DATE: APR/01/2013 DRAWN: Q.M.Chen PAGE: 5 OF 6 ERP: 1203012313

#### **PACKING & LABEL SPECIFICATIONS**

#### APB2012SURKCGKC







All design applications should refer to Kingbright application notes available at <a href="http://www.KingbrightUSA.com/ApplicationNotes">http://www.KingbrightUSA.com/ApplicationNotes</a>

SPEC NO: DSAM5537 APPROVED: WYNEC REV NO: V.2A CHECKED: Allen Liu DATE: APR/01/2013 DRAWN: Q.M.Chen PAGE: 6 OF 6 ERP: 1203012313